



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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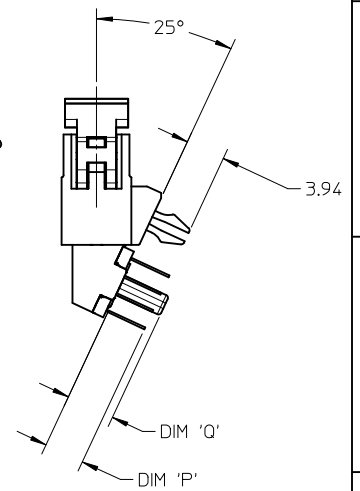
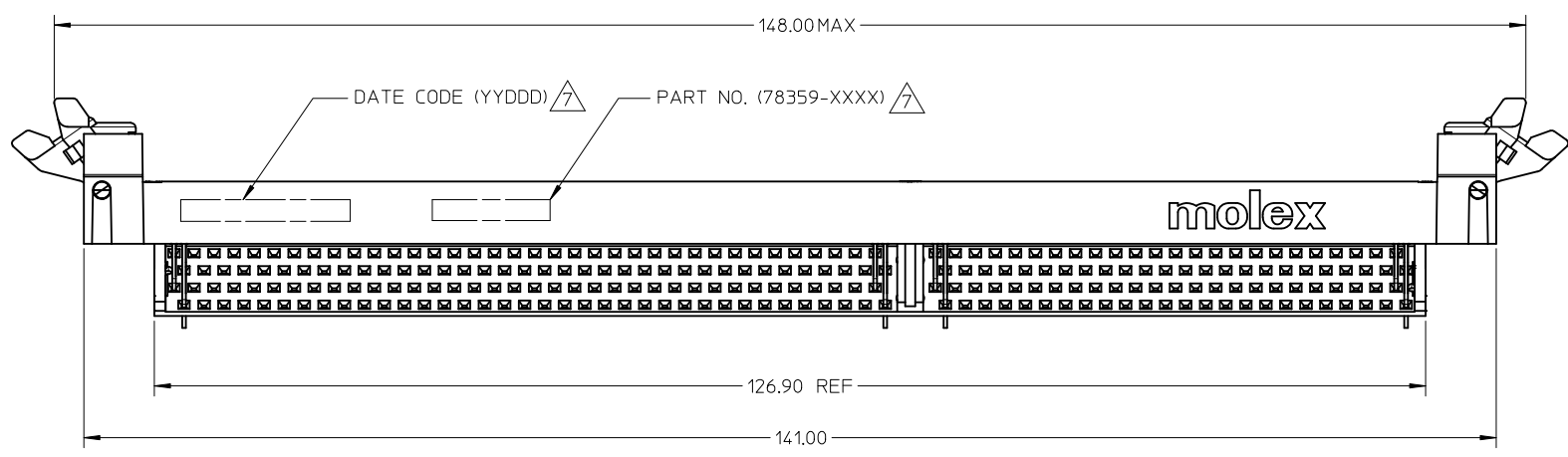
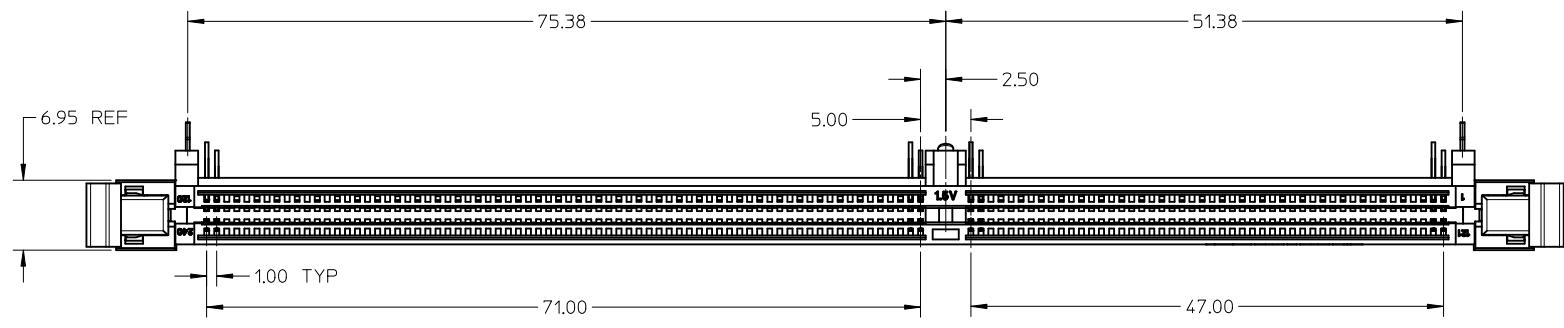
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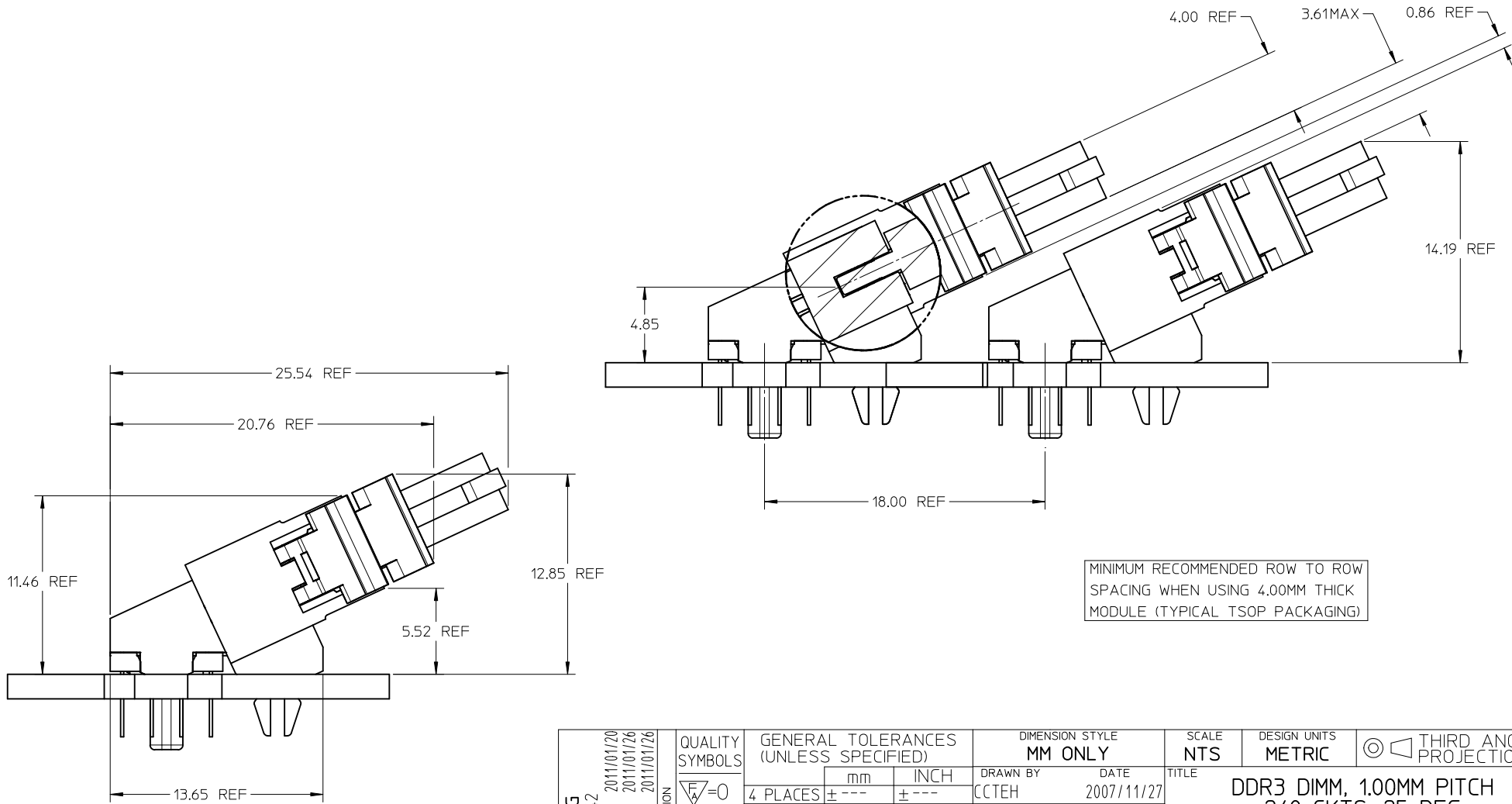
NOTES:

- MATERIALS:
HOUSING & BASEPLATE - LCP, GLASS-FILLED, UL94V-0, BLACK
LATCH - NYLON, GLASS-FILLED, UL94V-0, BLACK
TERMINALS & FORKLOCK - COPPER ALLOY
 - PLATING : CONTACT AREA - SEE TABLE IN SHEET 5
SOLDERTAIL - SEE TABLE IN SHEET 5
 - CARD SLOT ACCEPTS 1.27±0.10MM MODULE THICKNESS (MEASURE OVER PC PAD)
 - REFER TO PRODUCT SPECIFICATION PS-78359-001 FOR PERFORMANCE SPECIFICATION
 - RECOMMENDED MODULE CARD LAYOUT SHELL BE AS PER JEDEC MO-269
 - PRODUCT SHALL BE PACKED IN TRAY
- MOLEX LOGO , DATE CODE PART NUMBER INDICATED ON HOUSING

THIS DESIGN IS BASED ON DESIGN OBJECTIVES AND IS STRICTLY TENTATIVE. IT MAY CHANGE BASED ON RESULTS OF ADDITIONAL DESIGN REVIEWS & VERIFICATIONS.

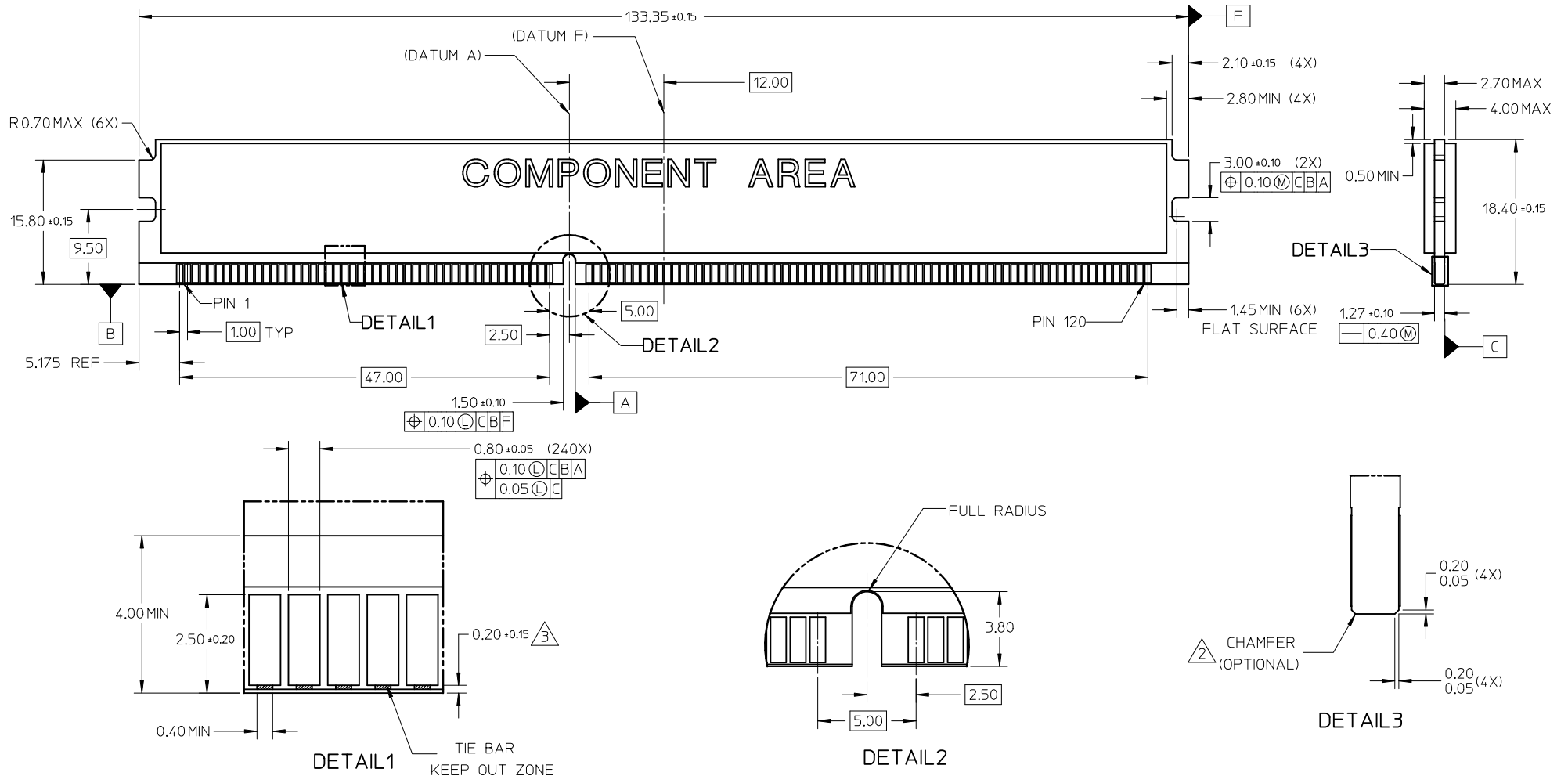
ADDED CORING EC NO: S2011-0442 DRW: CCTEH 2011/01/20 CHKD: CGTAN 2011/01/26 APPR: SHLENI 2011/01/26	DESCRIPTION QUALITY SYMBOLS $F_A=0$ $F_G=0$ $F_P=0$	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
			mm	INCH	DRAWN BY CCTEH	DATE 2007/11/27	TITLE DDR3 DIMM, 1.00MM PITCH 240 CKTS, 25 DEG T/H, VLP			
		4 PLACES ± --- ± ---			CHECKED BY CGTAN	DATE 2008/04/22	MOLEX INCORPORATED DOCUMENT NO. SD-78359-001 SHEET NO. 1 OF 5			
		3 PLACES ± --- ± ---			APPROVED BY SHLENI	DATE 2008/04/22				
2 PLACES ± 0.25 ± ---			MATERIAL NO.		SEE TABLE					
1 PLACE ± --- ± ---			ANGULAR ± 3 °		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				SIZE A3						

9 8 7 6 5 4 3 2 1



ADDED CORING EC NO: S2011-0442 DRWN: CTEH 2011/01/20 CHKD: CGTAN 2011/01/26 APPR: SHLENI 2011/01/26	QUALITY SYMBOLS $F_A=0$ $F_C=0$ $F_P=0$	GENERAL TOLERANCES (UNLESS SPECIFIED) <table border="1"> <thead> <tr> <th></th> <th>mm</th> <th>INCH</th> </tr> </thead> <tbody> <tr> <td>4 PLACES</td> <td>± ---</td> <td>± ---</td> </tr> <tr> <td>3 PLACES</td> <td>± ---</td> <td>± ---</td> </tr> <tr> <td>2 PLACES</td> <td>± 0.25</td> <td>± ---</td> </tr> <tr> <td>1 PLACE</td> <td>± ---</td> <td>± ---</td> </tr> </tbody> </table>		mm	INCH	4 PLACES	± ---	± ---	3 PLACES	± ---	± ---	2 PLACES	± 0.25	± ---	1 PLACE	± ---	± ---	DIMENSION STYLE MM ONLY	SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
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DESCRIPTION 2	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	DRAWN BY: CTEH CHECKED BY: CGTAN APPROVED BY: SHLENI	DATE: 2007/11/27 DATE: 2008/04/22 DATE: 2008/04/22	TITLE DDR3 DIMM, 100MM PITCH 240 CKTS, 25 DEG T/H, VLP	MATERIAL NO. SEE TABLE	DOCUMENT NO. SD-78359-001	SHEET NO. 2 OF 5														

MODULE CARD
DDR3 DUAL INLINE MEMORY MODULE FAMILY 1.00 CONTACT CENTERS

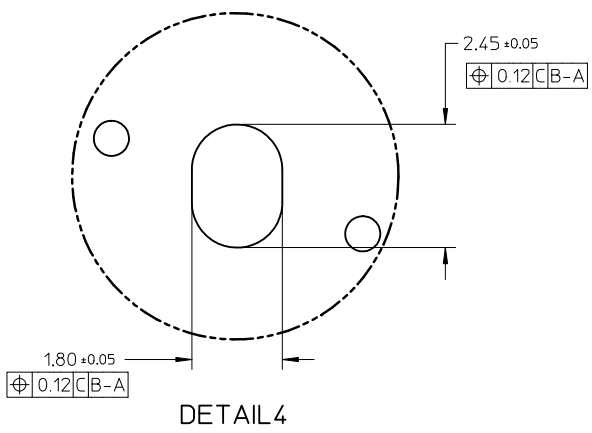
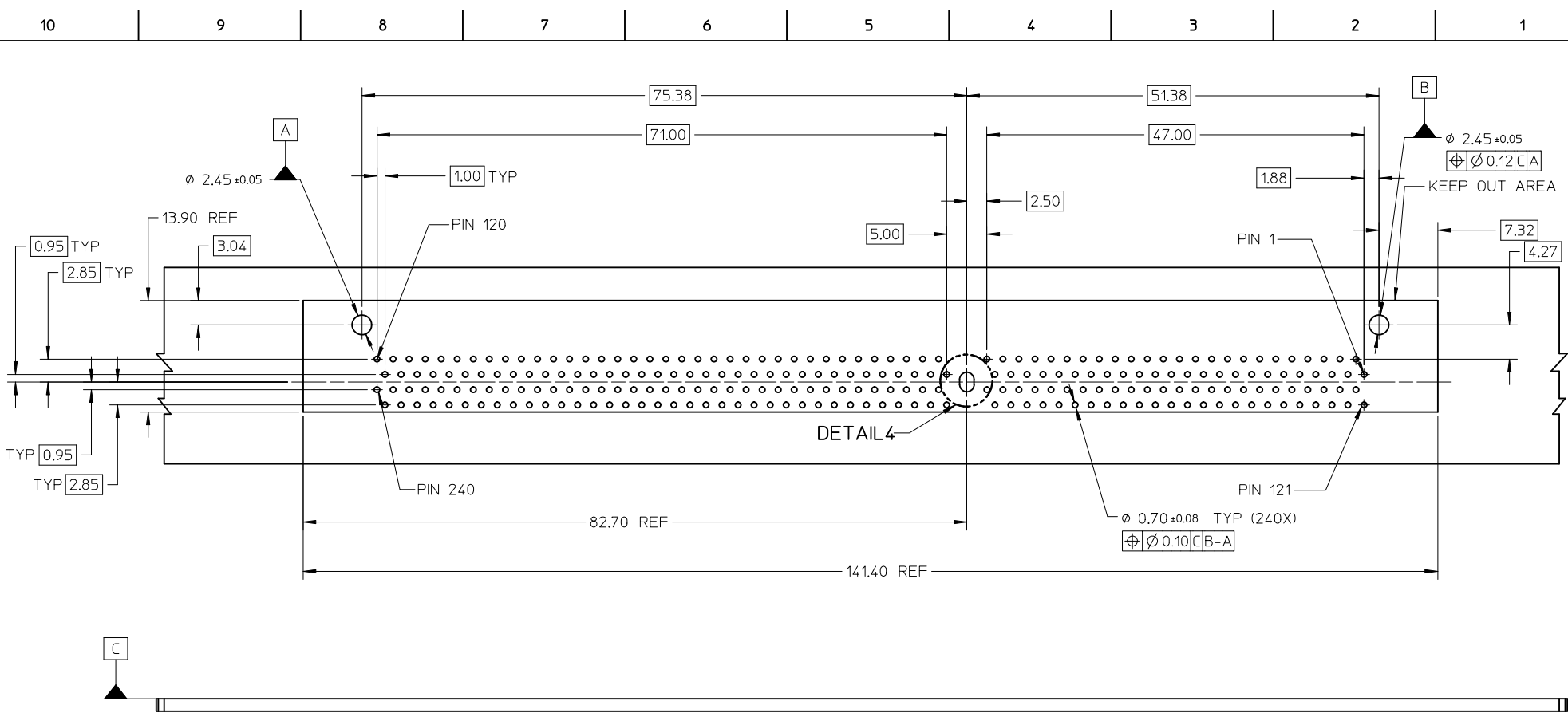


NOTES:

- RECOMMENDED PLATING FOR CONTACT PADS:
PREFERRED: 0.76 μM GOLD PLATING MIN
OVER 2.00 μM NICKEL
ALTERNATIVE: 0.05-0.75 μM GOLD PLATING
OVER 2.00 μM NICKEL MUST
USE AN ELECTRONIC CONTACT GRADE
CORROSIVE BARRIER LUBRICANT

- CHAMFER IS OPTIONAL AND IS NOT TO HIT THE GOLD PADS
- LEADING EDGE OF GOLD PADS SPECIFIED BY KEEP OUT ZONE
SHALL BE FREE OF BURRS AND EXTERNAL TIE BARS

ADDED CORING EC NO: S2011-0442 DRWN:CTEH 2011/01/26 CHKD:CGTAN 2011/01/26 APPR:SHLENI 2011/01/26	QUALITY SYMBOLS FA=0 FC=0 FB=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
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		1 PLACE	± ---	± ---	SEE TABLE		SD-78359-001		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		ANGULAR ± 3 °		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
						SHEET NO.		3 OF 5	



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			3 PLACES ± --- ± ---	APPROVED BY SHLENI	DATE 2008/04/22	MATERIAL NO. SEE TABLE	DOCUMENT NO. SD-78359-001	SHEET NO. 4 OF 5	
			2 PLACES ± 0.25 ± ---	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					
			1 PLACE ± --- ± ---						
			ANGULAR ± 3 °						

PART NO.	VOLTAGE KEY	DIM 'P'	DIM 'Q'	RECOMMENDED PCB THICKNESS	PLATING OPTION
78359-0001	CENTER (1.5V)	2.79	3.18	1.57	0.76µM / 30 Mmch MIN GOLD ON CONTACT 2.54µM / 100 Mmch MIN PURE TIN ON SOLDER TAILS 1.27µM / 50 Mmch MIN NICKEL UNDERPLATE
78359-0011		3.18	4.83	2.36	
78359-0111		4.00		2.59	

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		$\nabla_A = 0$ $\nabla_C = 0$ $\nabla_P = 0$	mm INCH 4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.25 ± --- 1 PLACE ± --- ± --- ANGULAR ± 3 °	MM ONLY	NTS	METRIC	DRAWN BY: CCTEH DATE: 2007/11/27 CHECKED BY: CGTAN DATE: 2008/04/22 APPROVED BY: SHLENI DATE: 2008/04/22	TITLE	DDR3 DIMM, 1.00MM PITCH 240 CKTS, 25 DEG T/H, VLP
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	SEE TABLE	MATERIAL NO.	DOCUMENT NO.	SHEET NO.	MOLEX INCORPORATED SD-78359-001 5 OF 5		
			SIZE: A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					